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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/789,423	02/27/2004	Harald Bottner	20659/0203719-US0	5684
38881	7590 02/28/2006		EXAMINER	
DARBY &	DARBY P.C.	SANDVIK, BENJAMIN P		
P.O. BOX 5257 NEW YORK, NY 10150-5257			ART UNIT	PAPER NUMBER
11211 10141	, 111 10100 000		2826	
		DATE MAILED: 02/28/2006		

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)				
Office Author Commence	10/789,423	BOTTNER ET AL.				
Office Action Summary	Examiner	Art Unit				
	Ben P. Sandvik	2826				
The MAILING DATE of this communication appears on the cover sheet with the correspondence address Period for Reply						
A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication. - If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication. - Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).						
Status						
1) Responsive to communication(s) filed on 19 De	Responsive to communication(s) filed on 19 December 2005.					
<u> </u>	<u> </u>					
<i>;</i> —	this application is in condition for allowance except for formal matters, prosecution as to the merits is					
,—	closed in accordance with the practice under Ex parte Quayle, 1935 C.D. 11, 453 O.G. 213.					
Disposition of Claims						
4)⊠ Claim(s) <u>1-22</u> is/are pending in the application.						
• • • • • • • • • • • • • • • • • • • •	4a) Of the above claim(s) <u>1,3 and 6-21</u> is/are withdrawn from consideration.					
5) Claim(s) is/are allowed.						
6)⊠ Claim(s) <u>2,4,5 and 22</u> is/are rejected.						
7) Claim(s) is/are objected to.						
	B) Claim(s) are subject to restriction and/or election requirement.					
Application Papers						
9) The specification is objected to by the Examiner.						
10) The drawing(s) filed on is/are: a) accepted or b) objected to by the Examiner.						
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).						
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).						
11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.						
Priority under 35 U.S.C. § 119						
 12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f). a) All b) Some * c) None of: 1. Certified copies of the priority documents have been received. 2. Certified copies of the priority documents have been received in Application No. 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)). * See the attached detailed Office action for a list of the certified copies not received. 						
Attachment(s) 1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date	4) Interview Summary Paper No(s)/Mail Da 5) Notice of Informal P 6) Other:					

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DETAILED ACTION

Response to Arguments

Applicant's arguments, filed 12/19/2005, with respect to the rejection(s) of claim(s) 2, 4, and 5 have been fully considered and are persuasive. Therefore, the rejection has been withdrawn. However, upon further consideration, a new ground(s) of rejection is made in view of Tauchi.

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claim 2, 4, 5, and 22 are rejected under 35 U.S.C. 103(a) as being unpatentable over Tauchi (U.S. Patent #5966939), in view of Hayes et al (U.S. Patent #6077380).

With respect to **claim 2**, Tauchi teaches a microelectromechanical component having at least one soldering layer for joining at least one further component, but does not teach a soldering layer comprising at least one of a eutectic mixture of gold and bismuth and a bismuth layer for producing a soldered joint with to a gold layer. Hayes teaches a component having at least one soldering layer for joining to at least one further component (Fig. 9a, the layer formed by balls 108), which component includes at least one soldering layer made from a solder comprising a eutectic mixture of gold and bismuth (Col

6 Ln 64 to Col 7 Ln 6). It would have been obvious to one of ordinary skill in the art at the time the invention was made to use a solder as taught by Hayes in the structure of Tauchi in order to optimize the fabrication process of the device.

With respect to **claim 5**, Tauchi teaches a soldered joint (Fig. 1, 22) that joins at least two components, at least one component comprising at least two substrates (Fig. 1, 11 and 12) joined together by said solder, and each substrate has a thermo electric material (Fig. 1, 25 and 26) arranged thereon; but does not teach a solder comprising a eutectic mixture of gold and bismuth. Hayes teaches a component having at least one soldering layer for joining to at least one further component (Fig. 9a, the layer formed by balls 108), which component includes at least one soldering layer made from a solder comprising a eutectic mixture of gold and bismuth (Col 6 Ln 64 to Col 7 Ln 6). It would have been obvious to one of ordinary skill in the art at the time the invention was made to use a solder as taught by Hayes in the structure of Tauchi in order to optimize the fabrication process of the device.

With respect to **claim 22**, Tauchi teaches that the at least one component has a thermal functionality (Col 3 Ln 43-46).

Claim 4 is rejected under 35 U.S.C. 103(a) as being unpatentable over Tauchi and Hayes, in view of Kuramoto (U.S. PG Pub #2001/0020744).

With respect to **claim 4**, Tauchi does not teach that at least one soldering layer, prior to the soldering operation, has a layer thickness of 100 nm to 10

micrometers. Kuramoto teaches a solder layer prior to soldering that has a thickness range of between 7 and 40 micrometers (Fig. 3, 14 and as set forth in claim 4). It would have been obvious to one of ordinary skill in the art at the time the invention was made to make the solder layer of Hayes to be 100 nm to 10 micrometers based on the teachings of Kuramoto in order to provide enough solder to make a reliable connection.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Ben P. Sandvik whose telephone number is (571) 272-8446. The examiner can normally be reached on Mon-Fri.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nathan Flynn can be reached on (571) 272-1915. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

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